4.10.2
Sentence beginning “Since level1 measurements ...” needs rework after comma.

4.10.3.2 and 4.10.3.3
Is “2**7-1” accepted usage?

4.12
Second sentence needs rework.

4.16
Third line “proagation”

Table 4
Differential to Common Mode: “sum of the difference” needs clarification.
FEXT: remove asterisk

6.4
Second paragraph: Change to “..... long enough to contain two complete transitions”

7.2.2.1
Add sentence: “It is permitted to use sample SP_Bulk_PP10 defined in 6.1.3.2.”

7.3.2.4 item 3)
Change to “...... falling edge are approximately as shown in figure 15.”

7.5.1.5 Technical issue
Methods for measuring Z and Td require floating the pairs not being measured. This section says “....the shield with all other conductors as conductor 3.” Using these conflicting methods, Td ≠ ZC. Prefer floating all other conductors unless there is a measurement issue.

7.6.2.4
Second paragraph: “varried” should be “varied”.

7.7.1
Last paragraph: Would like to see “... on each of the DATA (16 pairs), PARITY (2 PAIRS), ....”

7.7.2.5
a) Would like to see a WARNING to be sure probe polarity of victim signal not inadvertently reversed.
b) Do we want to correct stored trace section to show 18 aggressors? Presently we show 25.

9.2.3
a) Says “The test fixture may be constructed of semi-rigid coax, microstrip PCB, or stripline PCB.” BUT, the figure shows something very different. Eliminate “semi-rigid coax”.

b) The fixture shows chip capacitors. These would ruin TDR risetime if large values. If low values, the capacitors are useless. In either event, they should not be there.

c) Bulk cable and PCB impedance and Td measured with ‘other lines floating’. Here, tying other lines to ground through 61 Ohms risks a different answer for assembly versus bulk. Resistors should probably not be on this fixture.
d) Suggest entirely new figure 19 FIX_ASY_1 (below, created in PowerPoint). Perhaps the existing figure will be used as new figure (Standard Load).

```
DELAY CALIBRATION TRACES. DESIGNED TO APPROXIMATELY EQUAL DELAY THROUGH TWO FIXTURES WITHOUT DUT.

VERTICAL OR SMT SCSI CONNECTOR

ALL TRACE HAVE EQUAL DELAY (FOR SKEW)

CONNECTORS (SMA OR SMB) PROVIDED FOR DATA (18 PAIRS), PARITY (2 PAIRS), REQ, AND ACK. ALL OTHER SIGNALS FLOATING.
```

9.2.4
First paragraph, second sentence. Since this is used in an eye diagram measurement, wiring should be per Section 4.16. Grounds should be grounded. Be specific regarding treatment of DATA, PARITY, DIFFSENSE, TERMPWR, RESERVED, etc.

Last sentence: “This test fixture also serves as a standard load …...”
Is this true? If memory serves, only the link-end has an enabled terminator. Intermediate standard loads do not (?).

>> Now re-examine Table 9, Eye, Multi-drop. Is a non-terminated standard load required?

9.2.6
Figure 23: pins descending from TP-101 fixture – add note saying must be as short as possible.

Figure 24: add grounding dots and text same as figure 4 (6.2.4).
9.3.3 (SET_ASY_2)
Multiple problems figure 26. Replace this figure with exact copy of figure 7 (6.3.3).

9.3.4 (SET_ASY_3)
Figure 27 allows only point to point. No intermediate standard loads for multi-drop.

9.3.5 (SET_ASY_4)
Figure 28: All wrong. Replace baluns, attenuators, and matching networks with image from figure 22 – or – blocks referring to figure 24.

10.1.2.3
Remove all text.
Add “Use the same requirements as specified in 7.2.2.4 …”

10.1.2.4
Remove all text.
Add “Use the same requirements as specified in 7.2.2.5 …”

Add 10.1.2.5 Acceptable Values ….

10.1.3
Remove all text. (Presently refers back to 10.1.2, which is empty. Actual measurement procedure is different for multi-drop, which differs from point to point.)

Add Section 10.1.3.1 Test Fixtures for multi-drop assemblies
Add words: Test fixtures for multi-drop interconnect assemblies are defined in 9.2.3.

Add Section 10.1.3.2 Measurement equipment and setup for multi-drop assemblies
Add words: Measurement equipment for multi-drop interconnect assemblies are defined in 9.3.2.

Add Section 10.1.3.3 Calibration and verification procedure for multi-drop interconnect assemblies
Add “Use the same requirements as specified in 7.2.2.4 …”

Add Section 10.1.3.4 Test procedures and data output format for multi-drop interconnect assemblies
Add “Use the same requirements as specified in 7.2.3.5 …”

Add Section 10.1.3.5 Acceptable values

10.1.4
“Use the same procedures and equipment defined for multi-drop interconnect assemblies with appropriate modifications for the PCB structure being used.”

10.2.1
Second sentence:
This test is performed on bulk cable interconnect assemblies that are terminated with connectors in a point to point fashion consistent with SCSI signal assignments specified in SPI-x.

10.2.2.2
Eliminate 1), 2), 3)
10.2.2.3
Remove all text.
Add “Use the same requirements as specified in 7.3.2.4 ...”

10.2.2.4
Remove all text.
Add “Use the same requirements as specified in 7.3.2.5 ...”

10.2.3
Add “Use the same requirements as specified in 10.2.2 ...”
Remove all subsections 10.2.3.x except, perhaps, acceptable values.

10.3
10.3.1 First paragraph
Sentence “The time domain waveform is acquired ... set to trigger on the same part of the data pattern.” Triggering should be off the data clock. Triggering off the same part of the data pattern will not show the full eye (unless there is something unique with SCSI).

10.3.2.4 Last paragraph, last line. Spelling error hat that.

10.5
This section apparently uses an active termination load board (FIX_ASY_2, 9.2.4) as part of a network analyzer measurement. Does this really work???
Further, FIX_ASY_1 is suitable only for Impedance and Delay measurement.

Annex B NOT REVIEWED
Annex C
Improved Figure C.2 (from PowerPoint)

DISCONTINUITIES FORMED BY PINCHING SAMPLE BETWEEN TWO FINGERS. LEFT IS BEGINNING OF FLAT REGION, RIGHT IS END OF FLAT REGION

KNOWN LOCATION OF FLAT REGION. THE IMPEDANCE OF THE FLAT IS KNOWN TO BE HIGHER THAN THE IMPEDANCE OF THE TWIST.

SIGNAL LAUNCHED INTO TWIST

(STORED TRACES)
Improved Figure C.3 (from PowerPoint)

Annex C.2
a) Second to last paragraph, at end, add “Filtering the data does not remove the mirages.”
b) Last paragraph and figure C.4

Annex D Not reviewed